TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

# **TPC6004**

# Notebook PC Applications Portable Equipment Applications

- Low drain-source ON resistance: RDS (ON) = 19 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current:  $IDSS = 10 \mu A (max) (VDS = 20 V)$
- Enhancement mode:  $V_{th}$  = 0.5 to 1.2 V ( $V_{DS}$  = 10 V,  $I_{D}$  = 200  $\mu A$ )

#### Maximum Ratings (Ta = 25°C)

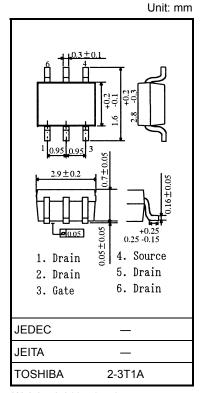
Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	20	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	20	V	
Gate-source voltage		V <sub>GSS</sub>	±12	V	
Drain current	DC (Note 1)	I <sub>D</sub>	6	A	
Drain current	Pulse (Note 1)	I <sub>DP</sub>	24		
Drain power dissipation	(t = 5 s) (Note 2a)	$P_{D}$	2.2	W	
Drain power dissipation	(t = 5 s) (Note 2b)	$P_{D}$	0.7	W	
Single pulse avalanche energy (Note 3)		E <sub>AS</sub>	5.8	mJ	
Avalanche current	I <sub>AR</sub>	3	Α		
Repetitive avalanche energy (Note 4)		E <sub>AR</sub>	0.22	mJ	
Channel temperature	T <sub>ch</sub>	150	°C		
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R <sub>th (ch-a)</sub>	56.8	°C/W	
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R <sub>th (ch-a)</sub>	178.5	°C/W	

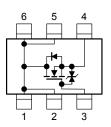
Note: Note 1, Note 2, Note 3, Note 4 and Note 5: See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.

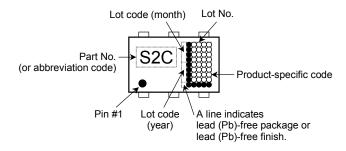


Weight: 0.011 g (typ.)

#### **Circuit Configuration**



# Marking (Note 5)



# **Electrical Characteristics (Ta = 25°C)**

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-OFF cu	ırrent	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	_	_	10	μА
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	$I_D = 10$ mA, $V_{GS} = 0$ V	20	_	_	V
		V <sub>(BR)DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	_	_	
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS}=10~V,~I_D=200~\mu A$	0.5	_	1.2	V
			$V_{GS} = 2.0 \text{ V}, I_D = 3 \text{ A}$	_	30	37	
Drain-source ON	resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 3 A	_	25	32	mΩ
			V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3 A	_	19	24	
Forward transfer admittance		Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	5.5	11	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1400	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	165	_	
Output capacitance		Coss	]	_	180	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{5}{\overset{\circ}{\overset{\circ}{\circ}}} V \stackrel{I_{D} = 3 \text{ A}}{\overset{\circ}{\overset{\circ}{\overset{\circ}{\circ}}}} V_{OUT}$ $\stackrel{G}{\overset{\circ}{\overset{\circ}{\overset{\circ}{\overset{\circ}{\circ}}}}} \stackrel{G}{\overset{\circ}{\overset{\circ}{\overset{\circ}{\overset{\circ}{\circ}}}}} \stackrel{G}{\overset{\circ}{\overset{\circ}{\overset{\circ}{\overset{\circ}{\circ}}}}} V_{OD} \simeq 10 \text{ V}$ $Duty \leq 1\%, \ t_{W} = 10 \ \mu s$	_	5	_	ns ns
	Turn-ON time	t <sub>on</sub>		_	10	_	
	Fall time	t <sub>f</sub>		_	14	_	
	Turn-OFF time	t <sub>off</sub>		_	60	_	
Total gate charge (gate-source plus gate-drain)		Qg			17		nC
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 16 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6 \text{ A}$	_	13		
Gate-drain ("miller") charge		Q <sub>gd</sub>	]	_	4	_	

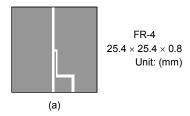
# Source-Drain Ratings and Characteristics (Ta = 25°C)

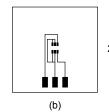
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Pulse drain reverse current (No	e 1)	I <sub>DRP</sub>	_	_	_	24	Α
Forward voltage (Diode)		V <sub>DSF</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



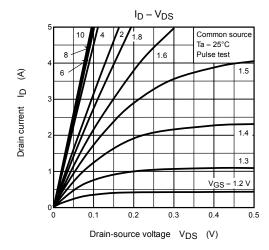


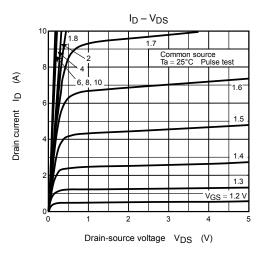
FR-4  $25.4 \times 25.4 \times 0.8$  Unit: (mm)

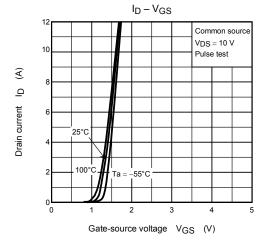
Note 3:  $V_{DD}$  = 16 V,  $T_{ch}$  = 25°C (initial), L = 0.5 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 3.0 A

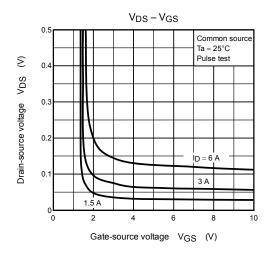
Note 4: Repetitive rating: pulse width limited by maximum channel temperature

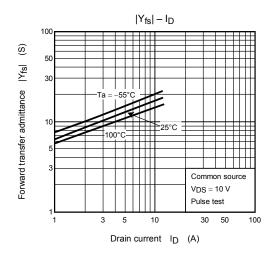
Note 5: • on lower left of the marking indicates Pin 1.

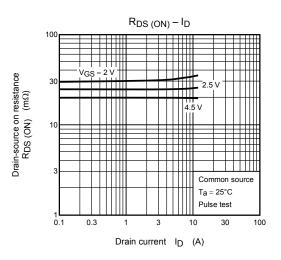




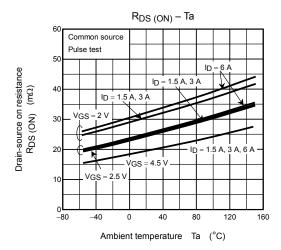


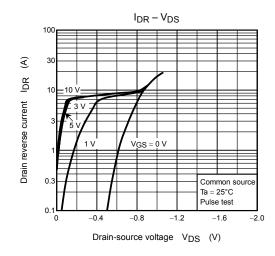


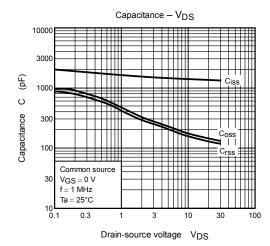


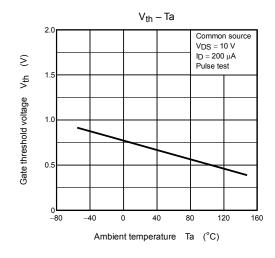


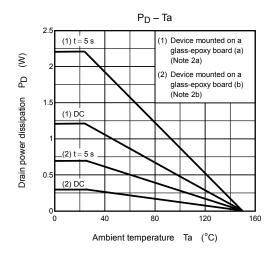
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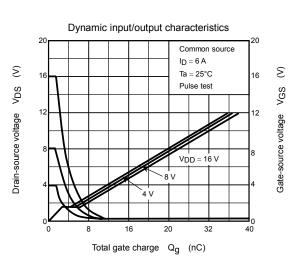




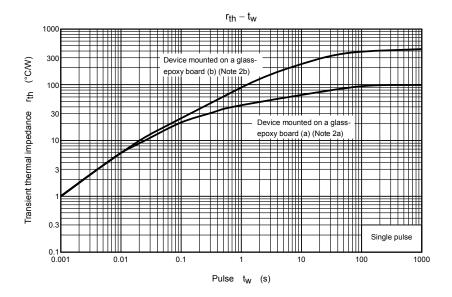


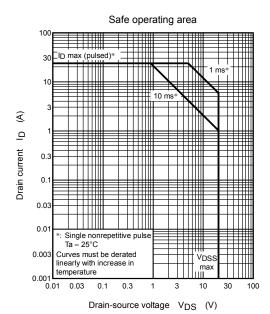






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Handbook" etc..

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